



UNIVERSAL ACTIVE FILTER

Check for Samples: [UAF42](#)

FEATURES

- **VERSATILE:**
 - Low-Pass, High-Pass
 - Band-Pass, Band-Reject
- **SIMPLE DESIGN PROCEDURE**
- **ACCURATE FREQUENCY AND Q:**
 - Includes On-Chip 1000pF $\pm 0.5\%$ Capacitors

APPLICATIONS

- **TEST EQUIPMENT**
- **COMMUNICATIONS EQUIPMENT**
- **MEDICAL INSTRUMENTATION**
- **DATA ACQUISITION SYSTEMS**
- **MONOLITHIC REPLACEMENT FOR UAF41**

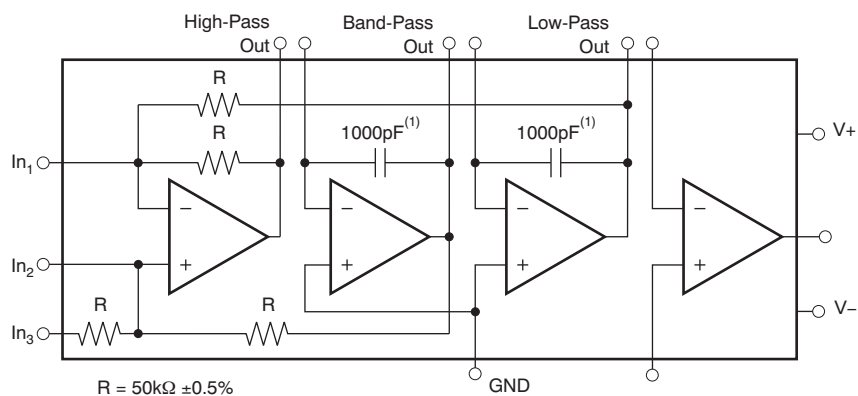
DESCRIPTION

The UAF42 is a universal active filter that can be configured for a wide range of low-pass, high-pass, and band-pass filters. It uses a classic state-variable analog architecture with an inverting amplifier and two integrators. The integrators include on-chip 1000pF capacitors trimmed to 0.5%. This architecture solves one of the most difficult problems of active filter design—obtaining tight tolerance, low-loss capacitors.

A DOS-compatible filter design program allows easy implementation of many filter types, such as Butterworth, Bessel, and Chebyshev. A fourth, uncommitted FET-input op amp (identical to the other three) can be used to form additional stages, or for special filters such as band-reject and Inverse Chebyshev.

The classical topology of the UAF42 forms a time-continuous filter, free from the anomalies and switching noise associated with switched-capacitor filter types.

The UAF42 is available in 14-pin plastic DIP and SOIC-16 surface-mount packages, specified for the -25°C to $+85^{\circ}\text{C}$ temperature range.


NOTE: (1) $\pm 0.5\%$.


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

All trademarks are the property of their respective owners.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of the Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

Copyright © 1992–2010, Texas Instruments Incorporated



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Over operating free-air temperature range unless otherwise noted.

	UAF42	UNIT
Power Supply Voltage	± 18	V
Input Voltage	$\pm V_S \pm 0.7$	V
Output Short-Circuit	Continuous	
Operating Temperature	-40 to $+85$	$^{\circ}\text{C}$
Storage Temperature	-40 to $+125$	$^{\circ}\text{C}$
Junction Temperature	$+125$	$^{\circ}\text{C}$

- (1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended period may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not supported.

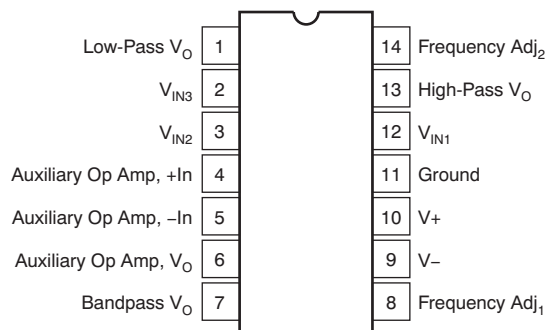
ORDERING INFORMATION⁽¹⁾

PRODUCT	PACKAGE-LEAD	PACKAGE DESIGNATOR	PACKAGE MARKING
UAF42AP	PDIP-14	N	UAF42AP
UAF42APG4			
UAF42AU	SOIC-16	DW	UAF42AU
UAF42AUE4			

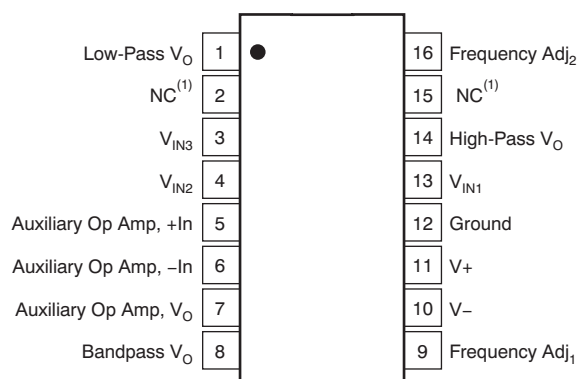
- (1) For the most current package and ordering information see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

PIN CONFIGURATIONS

**P PACKAGE
PDIP-14
(TOP VIEW)**



**U PACKAGE
SOIC-16
(TOP VIEW)**



NOTE: (1) NC = no connection. For best performance connect all NC pins to ground to minimize inter-lead capacitance.

ELECTRICAL CHARACTERISTICS

At $T_A = +25^\circ\text{C}$, and $V_S = \pm 15\text{V}$, unless otherwise noted.

PARAMETER	CONDITIONS	UAF42AP, AU			UNIT
		MIN	TYP	MAX	
FILTER PERFORMANCE					
Frequency Range, f_n			0 to 100		kHz
Frequency Accuracy vs Temperature	$f = 1\text{kHz}$		0.01	1	%/ $^\circ\text{C}$
Maximum Q			400		—
Maximum (Q • Frequency) Product			500		kHz
Q vs Temperature	$(f_o \cdot Q) < 10^4$		0.01		%/ $^\circ\text{C}$
	$(f_o \cdot Q) < 10^5$		0.025		%/ $^\circ\text{C}$
Q Repeatability	$(f_o \cdot Q) < 10^5$		2		%
Offset Voltage, Low-Pass Output				± 5	mV
Resistor Accuracy			0.5	1	%
OFFSET VOLTAGE⁽¹⁾					
Input Offset Voltage			± 0.5	± 5	mV
vs Temperature			± 3		$\mu\text{V}/^\circ\text{C}$
vs Power Supply	$V_S = \pm 6\text{V to } \pm 18\text{V}$	80	96		dB
INPUT BIAS CURRENT⁽¹⁾					
Input Bias Current	$V_{CM} = 0\text{V}$		10	50	pA
Input Offset Current	$V_{CM} = 0\text{V}$		5		pA
NOISE					
Input Voltage Noise					
Noise Density: $f = 10\text{Hz}$			25		$\text{nV}/\sqrt{\text{Hz}}$
Noise Density: $f = 10\text{kHz}$			10		$\text{nV}/\sqrt{\text{Hz}}$
Voltage Noise: BW = 0.1Hz to 10Hz			2		μV_{PP}
Input Bias Current Noise					
Noise Density: $f = 10\text{kHz}$			2		$\text{fA}/\sqrt{\text{Hz}}$
INPUT VOLTAGE RANGE⁽¹⁾					
Common-Mode Input Range			± 11.5		V
Common-Mode Rejection	$V_{CM} = \pm 10\text{V}$	80	96		dB
INPUT IMPEDANCE⁽¹⁾					
Differential			$10^{13} \parallel 2$		$\Omega \parallel \text{pF}$
Common-Mode			$10^{13} \parallel 6$		$\Omega \parallel \text{pF}$
OPEN-LOOP GAIN⁽¹⁾					
Open-Loop Voltage Gain	$V_O = \pm 10\text{V}, R_L = 2\text{k}\Omega$	90	126		dB
FREQUENCY RESPONSE					
Slew Rate			10		$\text{V}/\mu\text{s}$
Gain-Bandwidth Product	$G = +1$		4		MHz
Total Harmonic Distortion	$G = +1, f = 1\text{kHz}$		0.1		%
OUTPUT⁽¹⁾					
Voltage Output	$R_L = 2\text{k}\Omega$	± 11	± 11.5		V
Short Circuit Current			± 25		mA

(1) Specifications apply to uncommitted op amp, A_4 . The three op amps forming the filter are identical to A_4 but are tested as a complete filter.

ELECTRICAL CHARACTERISTICS (continued)At $T_A = +25^\circ\text{C}$, and $V_S = \pm 15\text{V}$, unless otherwise noted.

PARAMETER	CONDITIONS	UAF42AP, AU			UNIT
		MIN	TYP	MAX	
POWER SUPPLY					
Specified Operating Voltage			± 15		V
Operating Voltage Range		± 6		± 18	V
Current			± 6	± 7	mA
TEMPERATURE RANGE					
Specified		-25		$+85$	$^\circ\text{C}$
Operating		-25		$+85$	$^\circ\text{C}$
Storage		-40		$+125$	$^\circ\text{C}$
Thermal Resistance, θ_{JA}			100		$^\circ\text{C/W}$

APPLICATION INFORMATION

The UAF42 is a monolithic implementation of the proven state-variable analog filter topology. This device is pin-compatible with the popular UAF41 analog filter, and it provides several improvements.

The slew rate of the UAF42 has been increased to 10V/μs, versus 1.6V/μs for the UAF41. Frequency • Q product of the UAF42 has been improved, and the useful natural frequency extended by a factor of four to 100kHz. FET input op amps on the UAF42 provide very low input bias current. The monolithic construction of the UAF42 provides lower cost and improved reliability.

DESIGN PROGRAM

Application report [SBFA002](#) (available for download at www.ti.com) and a computer-aided design program also available from Texas Instruments, make it easy to design and implement many kinds of active filters. The DOS-compatible program guides you through the design process and automatically calculates component values.

Low-pass, high-pass, band-pass and band-reject (notch) filters can be designed. The program supports the three most commonly-used all-pole filter types: Butterworth, Chebyshev and Bessel. The less-familiar inverse Chebyshev is also supported, providing a smooth passband response with ripple in the stop band.

With each data entry, the program automatically calculates and displays filter performance. This feature allows a spreadsheet-like *what-if* design approach. For example, a user can quickly determine, by trial and error, how many poles are required for a desired attenuation in the stopband. Gain/phase plots may be viewed for any response type.

The basic building element of the most commonly-used filter types is the second-order section. This section provides a complex-conjugate pair of poles. The natural frequency, ω_n , and Q of the pole pair determine the characteristic response of the section. The low-pass transfer function is shown in [Equation 1](#):

$$\frac{V_O(s)}{V_I(s)} = \frac{A_{LP}\omega_n^2}{s^2 + s\omega_n/Q + \omega_n^2} \quad (1)$$

The high-pass transfer function is given by [Equation 2](#):

$$\frac{V_{HP}(s)}{V_I(s)} = \frac{A_{HP}s^2}{s^2 + s\omega_n/Q + \omega_n^2} \quad (2)$$

The band-pass transfer function is calculated using [Equation 3](#):

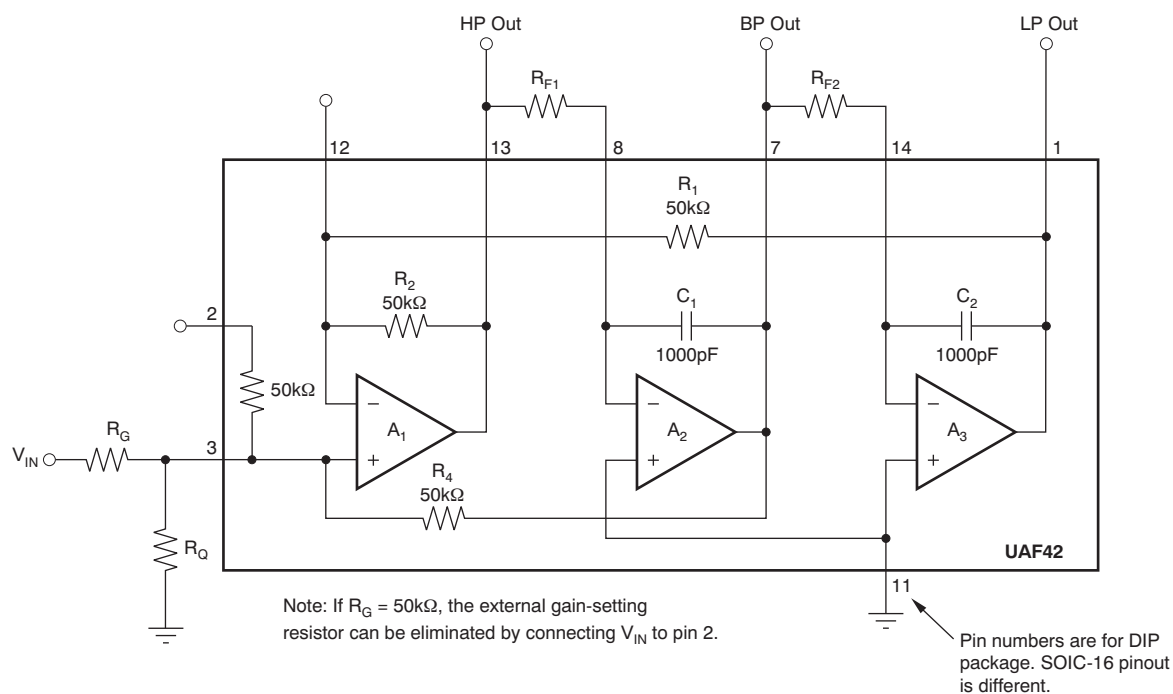
$$\frac{V_{BP}(s)}{V_I(s)} = \frac{A_{BP}(\omega_n/Q)s}{s^2 + s\omega_n/Q + \omega_n^2} \quad (3)$$

A band-reject response is obtained by summing the low-pass and high-pass outputs, yielding the transfer function shown in [Equation 4](#):

$$\frac{V_{BR}(s)}{V_I(s)} = \frac{A_{BR}(s^2 + \omega_n^2)}{s^2 + s\omega_n/Q + \omega_n^2} \quad (4)$$

The most common filter types are formed with one or more cascaded second-order sections. Each section is designed for ω_n and Q according to the filter type (Butterworth, Bessel, Chebyshev, etc.) and cutoff frequency. While tabulated data can be found in virtually any filter design text, the design program eliminates this tedious procedure.

Second-order sections may be noninverting ([Figure 1](#)) or inverting ([Figure 2](#)). Design equations for these two basic configurations are shown for reference. The design program solves these equations, providing complete results, including component values.



Design Equations

1. $\omega_n^2 = \frac{R_2}{R_1 R_{F1} R_{F2} C_1 C_2}$
2. $Q = \frac{1 + \frac{R_4 (R_G + R_Q)}{R_G R_Q}}{1 + \frac{R_2}{R_1}} \left(\frac{R_2 R_{F1} C_1}{R_1 R_{F2} C_2} \right)^{1/2}$
3. $QA_{LP} = QA_{HP} \left(\frac{R_1}{R_2} \right) = A_{BP} \left(\frac{R_1 R_{F1} C_1}{R_2 R_{F2} C_2} \right)^{1/2}$
4. $A_{LP} = \frac{1 + \frac{R_1}{R_2}}{R_G \left(\frac{1}{R_G} + \frac{1}{R_Q} + \frac{1}{R_4} \right)}$
5. $A_{HP} = \frac{R_2}{R_1} A_{LP} = \frac{1 + \frac{R_2}{R_1}}{R_G \left(\frac{1}{R_G} + \frac{1}{R_Q} + \frac{1}{R_4} \right)}$
6. $A_{BP} = \frac{R_4}{R_G}$

Figure 1. Noninverting Pole-Pair

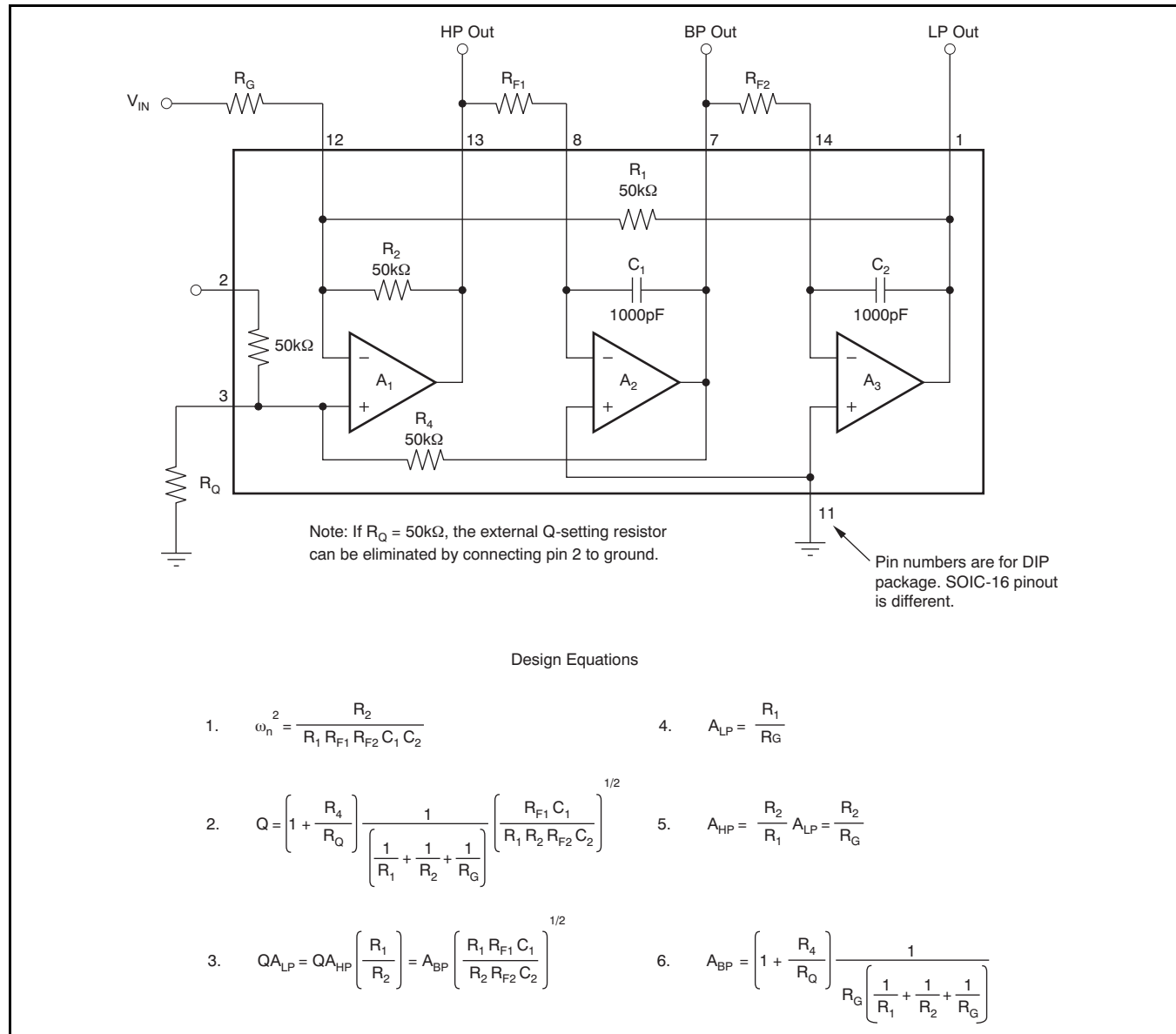


Figure 2. Inverting Pole-Pair

REVISION HISTORY

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision A (November, 2007) to Revision B	Page
• Corrected package marking information shown in <i>Ordering Information</i> table	2

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
UAF42AP	Active	Production	PDIP (N) 14	25 TUBE	Yes	Call TI	N/A for Pkg Type	-	UAF42AP
UAF42AP.A	Active	Production	PDIP (N) 14	25 TUBE	Yes	Call TI	N/A for Pkg Type	-25 to 85	UAF42AP
UAF42AU	Active	Production	SOIC (DW) 16	40 TUBE	Yes	NIPDAU	Level-3-260C-168 HR	-25 to 85	UAF42AU
UAF42AU.A	Active	Production	SOIC (DW) 16	40 TUBE	Yes	NIPDAU	Level-3-260C-168 HR	-25 to 85	UAF42AU

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

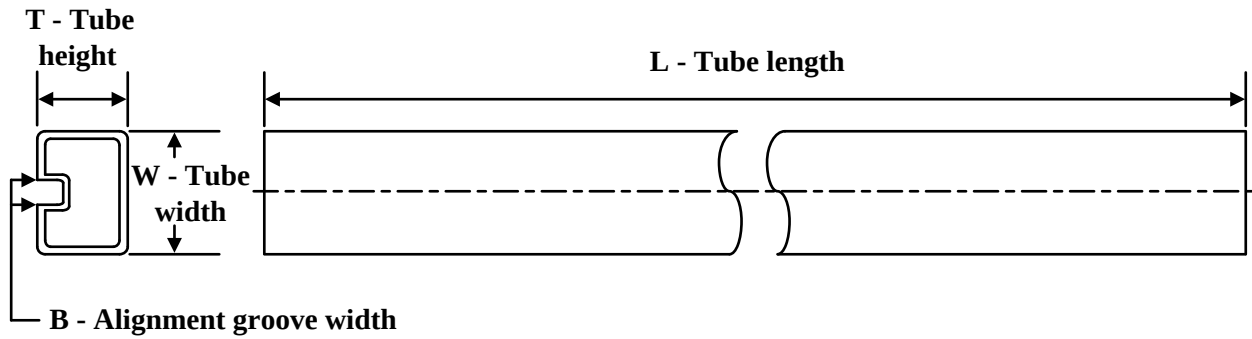
⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
UAF42AP	N	PDIP	14	25	506	13.97	11230	4.32
UAF42AP.A	N	PDIP	14	25	506	13.97	11230	4.32
UAF42AU	DW	SOIC	16	40	507	12.83	5080	6.6
UAF42AU.A	DW	SOIC	16	40	507	12.83	5080	6.6

GENERIC PACKAGE VIEW

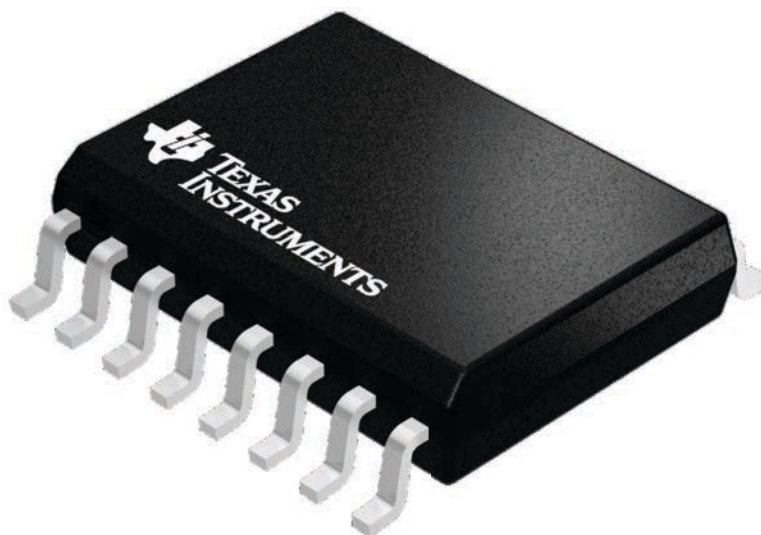
DW 16

SOIC - 2.65 mm max height

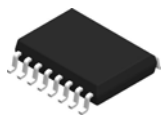
7.5 x 10.3, 1.27 mm pitch

SMALL OUTLINE INTEGRATED CIRCUIT

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



4224780/A

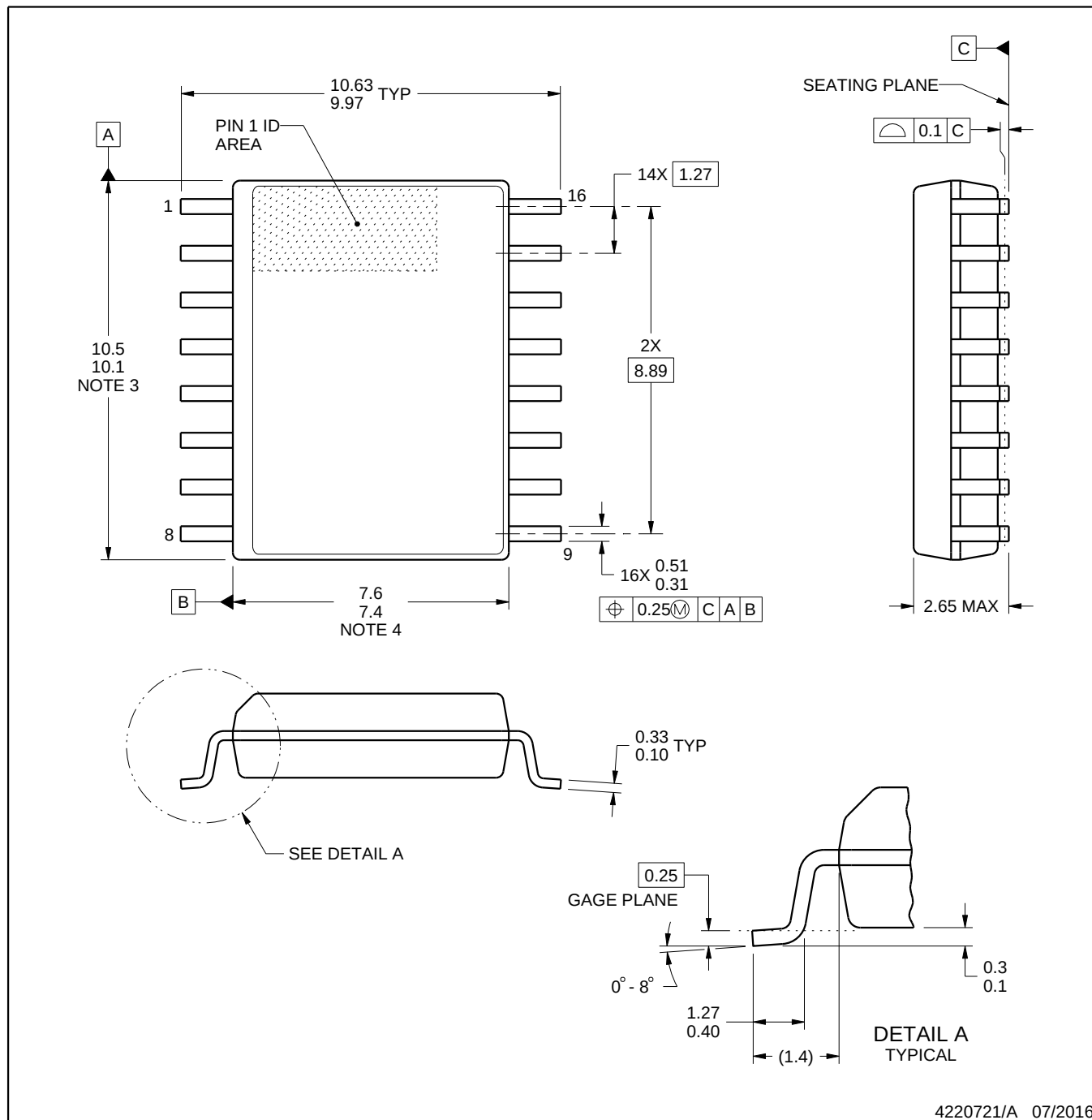


DW0016A

PACKAGE OUTLINE

SOIC - 2.65 mm max height

SOIC



4220721/A 07/2016

NOTES:

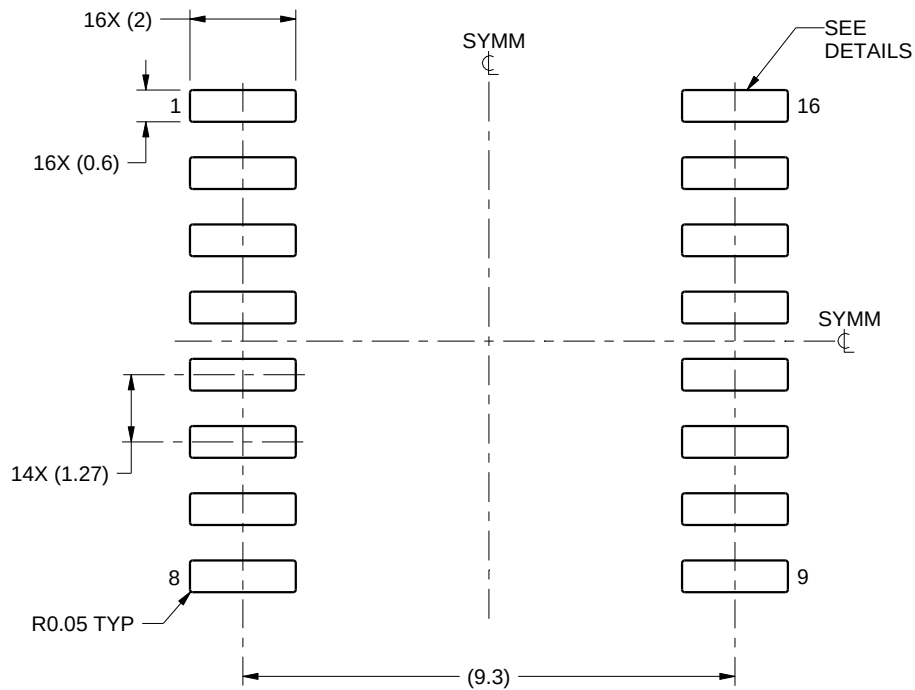
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.
5. Reference JEDEC registration MS-013.

EXAMPLE BOARD LAYOUT

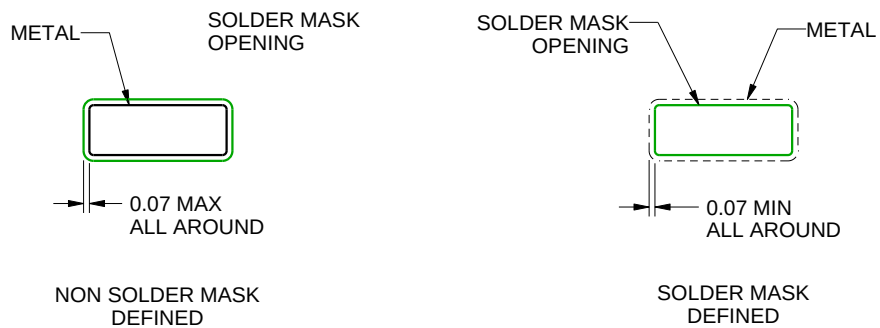
DW0016A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE
SCALE:7X



SOLDER MASK DETAILS

4220721/A 07/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

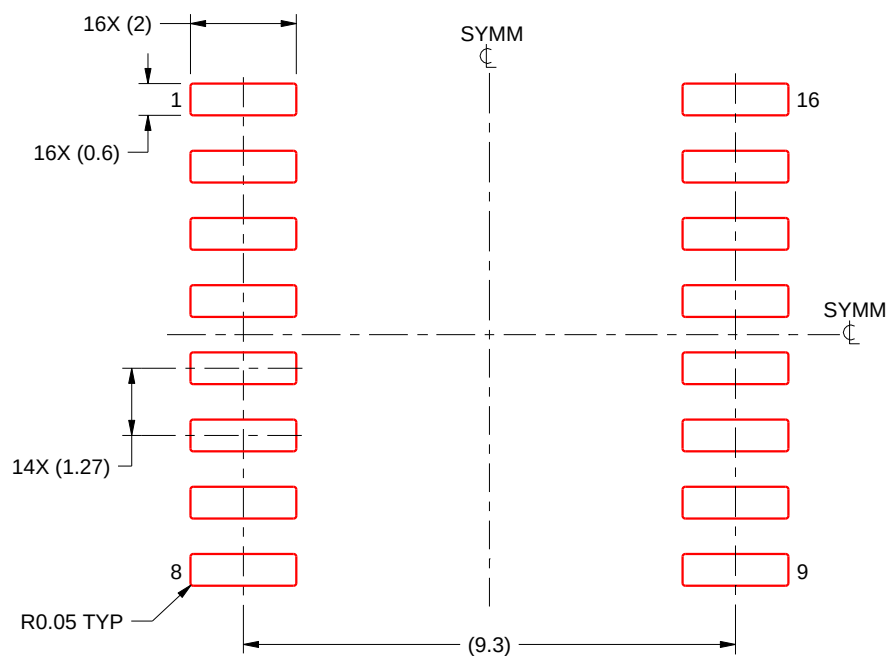
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DW0016A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:7X

4220721/A 07/2016

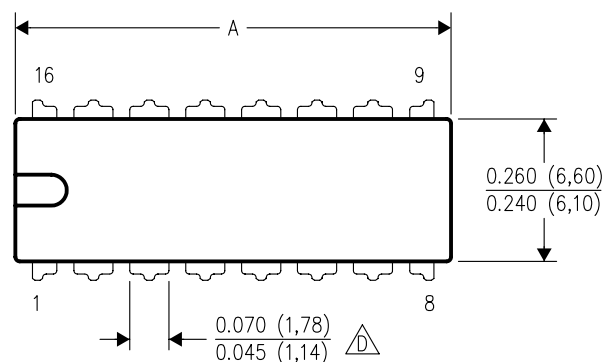
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

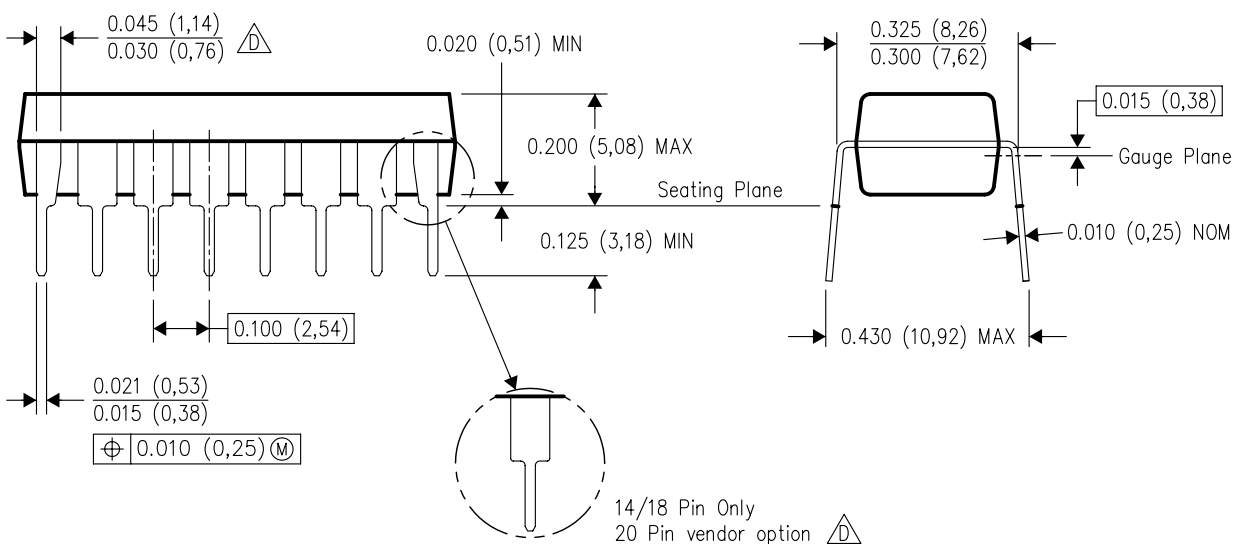
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

NOTES:

- A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
-  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 The 20 pin end lead shoulder width is a vendor option, either half or full width.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you fully indemnify TI and its representatives against any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#), [TI's General Quality Guidelines](#), or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products. Unless TI explicitly designates a product as custom or customer-specified, TI products are standard, catalog, general purpose devices.

TI objects to and rejects any additional or different terms you may propose.

Copyright © 2026, Texas Instruments Incorporated

Last updated 10/2025